

EL 844091657

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. .... 09/148,723  
Priority Filing Date ..... September 3, 1998  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Priority Group Art Unit ..... 3729  
Priority Examiner ..... A. Tugbang  
Attorney's Docket No. .... MI22-1839  
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

**PRELIMINARY AMENDMENT**

To: Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D.  
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Sir:

This is a preliminary amendment accompanying a Request for Continuation Application for the above-entitled patent application. Prior to examining the application, please enter the following amendments.

**AMENDMENTS**